



Material Content Data Sheet



Sales Product Name		TLE9255WSK		Issued		3. July 2019		
MA#		MA001593808						
Package		PG-DSO-14-39		Weight*		144.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.199	0.83	0.83	8275	8275
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		111	
	non noble metal	zinc	7440-66-6	0.065	0.04		445	
	non noble metal	iron	7439-89-6	1.290	0.89		8902	
wire	non noble metal	copper	7440-50-8	52.389	36.15	37.09	361464	370922
	noble metal	gold	7440-57-5	0.295	0.20	0.20	2035	2035
	encapsulation	organic material	carbon black	1333-86-4	0.175	0.12		1206
encapsulation	plastics	epoxy resin	-	8.040	5.55		55472	
	inorganic material	silicondioxide	60676-86-0	79.176	54.62	60.29	546282	602960
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8460	8460
plating	noble metal	silver	7440-22-4	0.552	0.38	0.38	3808	3808
glue	plastics	epoxy resin	-	0.128	0.09		885	
	noble metal	silver	7440-22-4	0.385	0.27	0.36	2655	3540
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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